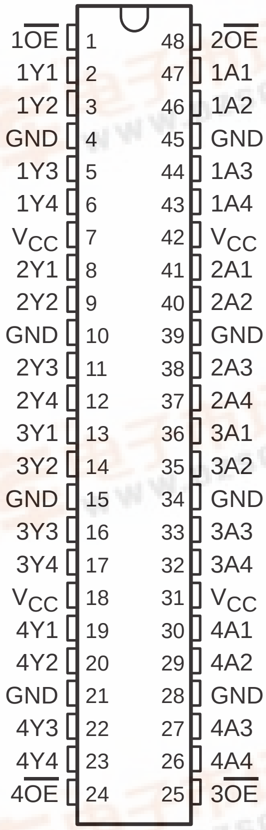
SN74LVCZ16240A
16-BIT BUFFER/DRIVER WITH 3-STATE OUTPUTS

SCES276B – JUNE 1999 – REVISED MARCH 2000

- **Member of the Texas Instruments *Widebus*™ Family**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) Submicron Process**
- **Typical V_{OLP} (Output Ground Bounce) <0.8 V at V_{CC} = 3.3 V, T_A = 25°C**
- **Typical V_{OHV} (Output V_{OH} Undershoot) >2 V at V_{CC} = 3.3 V, T_A = 25°C**
- **I_{off} and Power-Up 3-State Support Hot Insertion**
- **Supports Mixed-Mode Signal Operation on All Ports (5-V Input/Output Voltage With 3.3-V V_{CC})**
- **Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II**
- **ESD Protection Exceeds JESD 22**
  - **2000-V Human-Body Model (A114-A)**
  - **200-V Machine Model (A115-A)**
  - **1000-V Charged-Device Model (C101)**
- **Package Options Include Plastic Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages**

DGG OR DL PACKAGE
(TOP VIEW)



description

This 16-bit buffer/driver is designed for 3-V to 3.6-V V_{CC} operation.

The SN74LVCZ16240A is designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

The device can be used as four 4-bit buffers, two 8-bit buffers, or one 16-bit buffer. This device provides inverting outputs and symmetrical active-low output-enable ($\overline{\text{OE}}$) inputs.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of these devices as translators in a mixed 3.3-V/5-V system environment.

When V_{CC} is between 0 and 1.5 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.5 V, $\overline{\text{OE}}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

This device is fully specified for hot-insertion applications using I_{off} and power-up 3-state. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

The SN74LVCZ16240A is characterized for operation from –40°C to 85°C.

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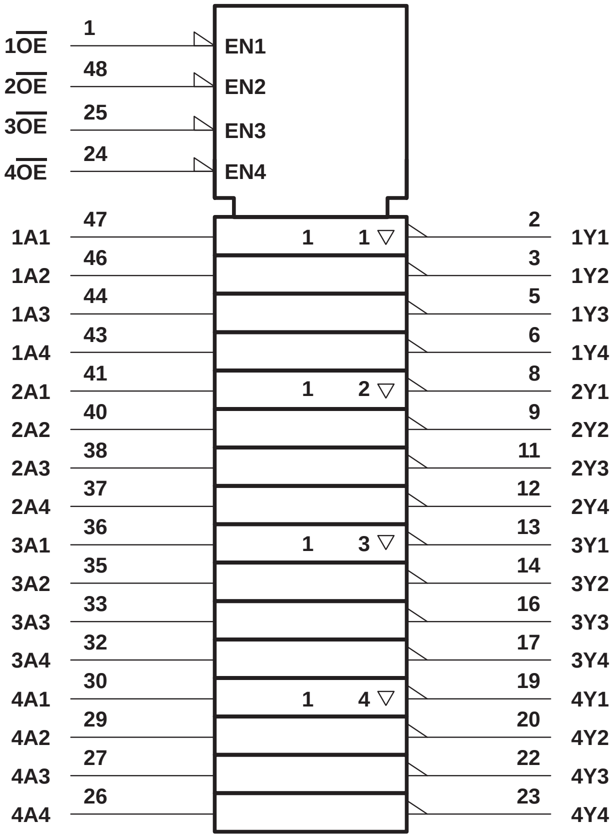
FUNCTION TABLE
(each 4-bit buffer)

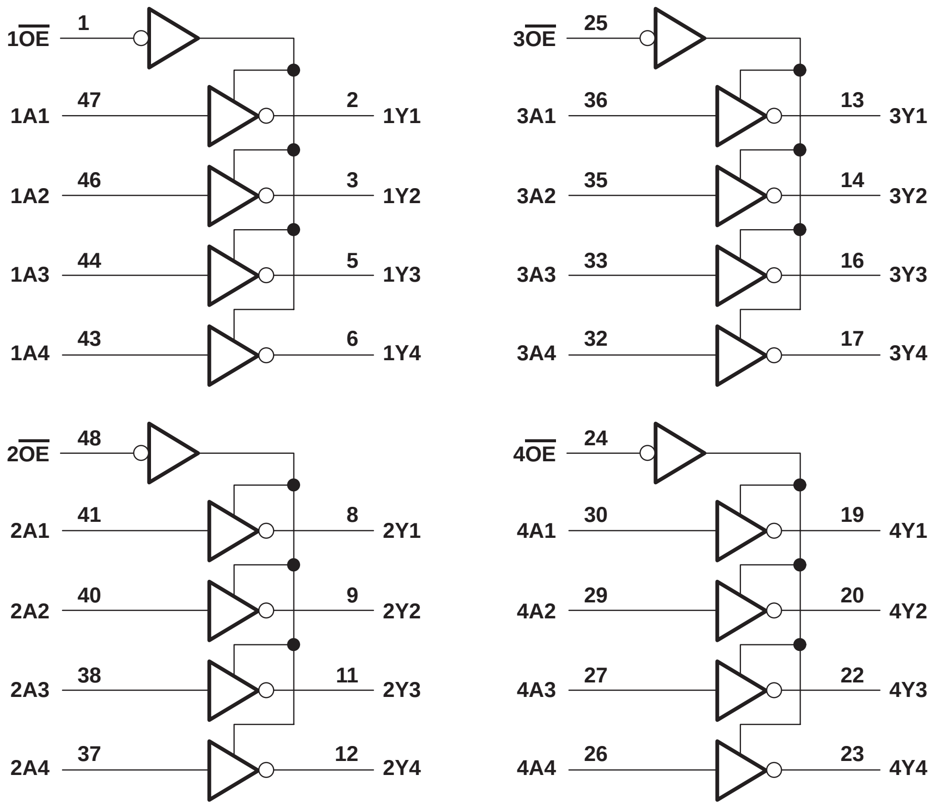
INPUTS		OUTPUT
$\overline{\text{OE}}$	**A**	**Y**
L	H	L
L	L	H
H	X	Z

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}		–0.5 V to 6.5 V
Input voltage range, V_I (see Note 1)		–0.5 V to 6.5 V
Voltage range applied to any output in the high-impedance or power-off state, V_O (see Note 1)		–0.5 V to 6.5 V
Voltage range applied to any output in the high or low state, V_O (see Notes 1 and 2)		–0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$)		–50 mA
Output clamp current, I_{OK} ($V_O < 0$)		–50 mA
Continuous output current, I_O		±50 mA
Continuous current through each V_{CC} or GND		±100 mA
Package thermal impedance, θ_{JA} (see Note 3):	DGG package	70°C/W
	DL package	63°C/W
Storage temperature range, T_{stg}		–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The value of V_{CC} is provided in the recommended operating conditions table.
3. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
V_{CC}	Supply voltage		3	3.6	V
V_{IH}	High-level input voltage	V_{CC} = 3 V to 3.6 V	2		V
V_{IL}	Low-level input voltage	V_{CC} = 3 V to 3.6 V		0.8	V
V_I	Input voltage		0	5.5	V
V_O	Output voltage	High or low state	0	V_{CC}	V
		3-state	0	5.5	
I_{OH}	High-level output current	V_{CC} = 3 V		–24	mA
I_{OL}	Low-level output current	V_{CC} = 3 V		24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate			10	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate		150		µs/V
T_A	Operating free-air temperature		–40	85	°C

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		V_{CC}	MIN	TYP†	MAX	UNIT
V_{OH}	I_{OH} = –100 µA		3 V to 3.6 V	V_{CC}–0.2			V
	I_{OH} = –12 mA		3 V	2.4			
	I_{OH} = –24 mA		3 V	2.2			
V_{OL}	I_{OL} = 100 µA		3 V to 3.6 V			0.2	V
	I_{OL} = 12 mA		3 V			0.4	
	I_{OL} = 24 mA		3 V			0.55	
I_I	V_I = 0 to 5.5 V		3.6 V			±5	µA
I_{off}	V_I or V_O = 5.5 V		0			±5	µA
I_{OZ}	V_O = 0 to 5.5 V		3.6 V			±5	µA
I_{OZPU}	V_O = 0.5 to 2.5 V,	$\overline{OE}$ = don't care	0 to 1.5 V			±5	µA
I_{OZPD}	V_O = 0.5 to 2.5 V,	$\overline{OE}$ = don't care	1.5 V to 0			±5	µA
I_{CC}	$V_I = V_{CC}$ or GND	$I_O = 0$	3.6 V			100	µA
	$3.6\text{ V} \le V_I \le 5.5\text{ V}$‡					100	
ΔI_{CC}	One input at V_{CC} – 0.6 V,	Other inputs at V_{CC} or GND	3 V to 3.6 V			100	µA
C_i	$V_I = V_{CC}$ or GND		3.3 V		4.5		pF
C_o	$V_O = V_{CC}$ or GND		3.3 V		6		pF

† All typical values are at V_{CC} = 3.3 V, T_A = 25°C.
‡ This applies in the disabled state only.

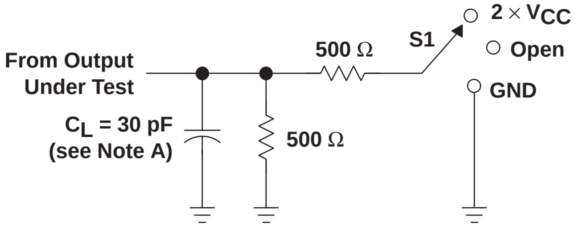
switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 3.3 V ± 0.3 V		UNIT
			MIN	MAX	
t_{pd}	A or B	B or A	1	4.2	ns
t_{en}	$\overline{OE}$	A or B	1.5	4.7	ns
t_{dis}	$\overline{OE}$	A or B	1.5	5.9	ns

operating characteristics, T_A = 25°C

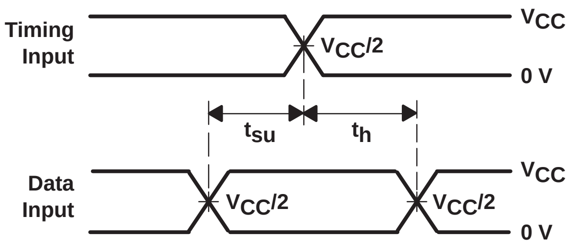
PARAMETER			TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per buffer/driver	Outputs enabled	f = 10 MHz	31	pF
		Outputs disabled		3.5	

PARAMETER MEASUREMENT INFORMATION
V_{CC} = 3.3 V ± 0.3 V

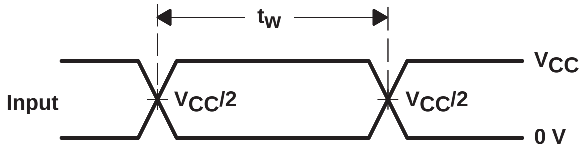


LOAD CIRCUIT

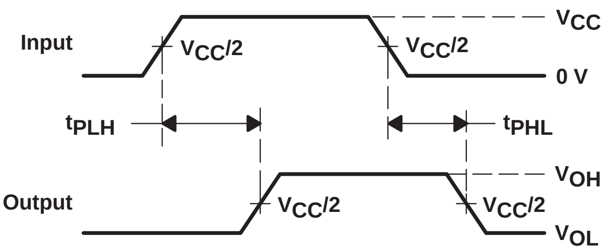
TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	GND



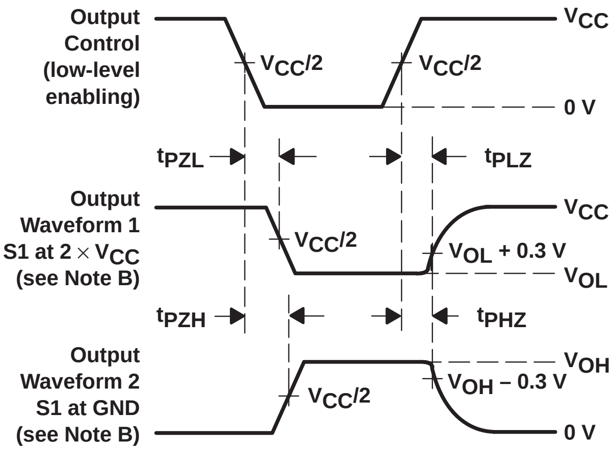
VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

NOTES:
- A. C_L includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, $t_r \le 2$ ns, $t_f \le 2$ ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
- F. t_{PZL} and t_{PZH} are the same as t_{en}.
- G. t_{PLH} and t_{PHL} are the same as t_{pd}.

Figure 1. Load Circuit and Voltage Waveforms

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